

運用於VCP的新世代電鍍錫技術

New Tin Plating Technology for VCP Application



SOLDERON™ VP-200 Tin Electroplating Bath

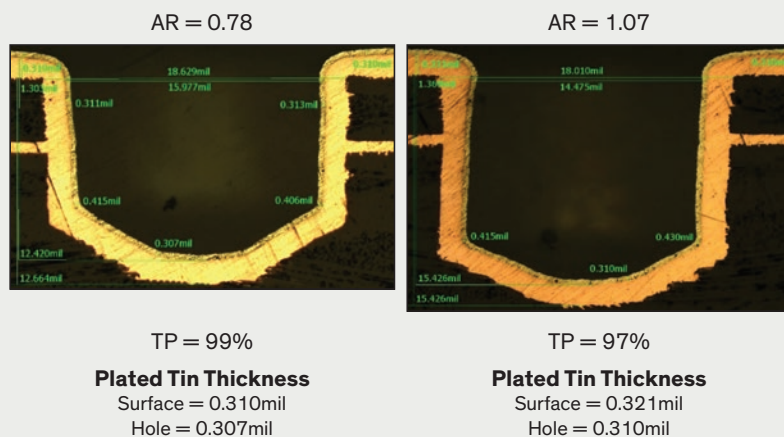
Dow Electronical Material offers SOLDERON™ VP-200 as new Tin plating product with characteristic of high performance, environmental friendliness, and low foaming. This product is designed to VCP application.

陶氏化學電子材料提供 SOLDERON VP-200具有高效能,環保和低泡沫特性運用於VCP的新世代電鍍錫技術.

Advantage of New Tin Process 新電鍍錫製程的特性

- Eco-friendly formulation
環保導向
 - NPE/APE free
不使用壬基苯酚類之界面活性劑
- Higher alkaline etching resistant
高抗鹼能力
 - Uniform, large and well-polygonized deposit at all range of current density
在不同電流密度下為緊密的多邊形晶格的鍍錫層結構
- Low foaming
低泡沫特性
 - Suitable to VCP line
適用於VCP線
- Robust to organic contamination from dry film leaching
對乾膜析出的有機汙染具有高容忍度

TP performance at different Aspect Ratio of M/C drilling hole 在不同縱橫比的機鑽盲孔之深鍍能力表現



Plating appearance and morphology 鍍層外觀和表面形貌

